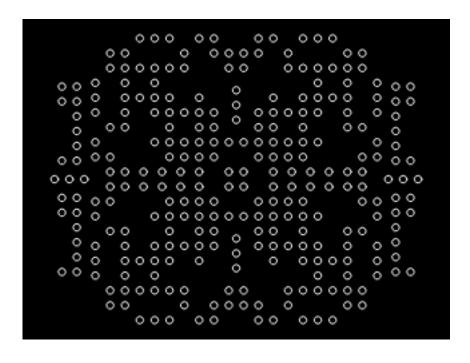
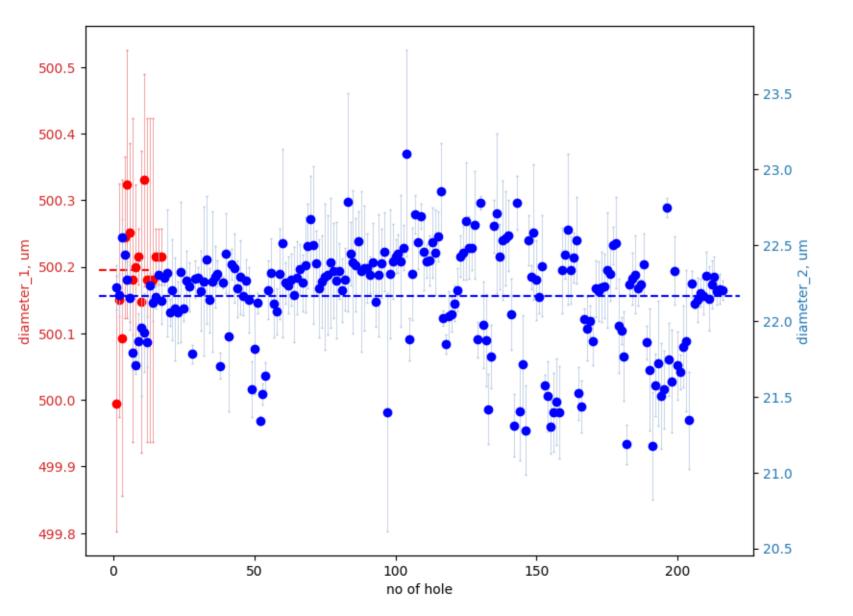
Date: 2022-11-24

Glass micromachining

280 holes (dia 100 um) in fused silica glass

Wafer thickness 1 mm Smooth sidewalls, Ra <0.5 um Positional accuracy ±3 um





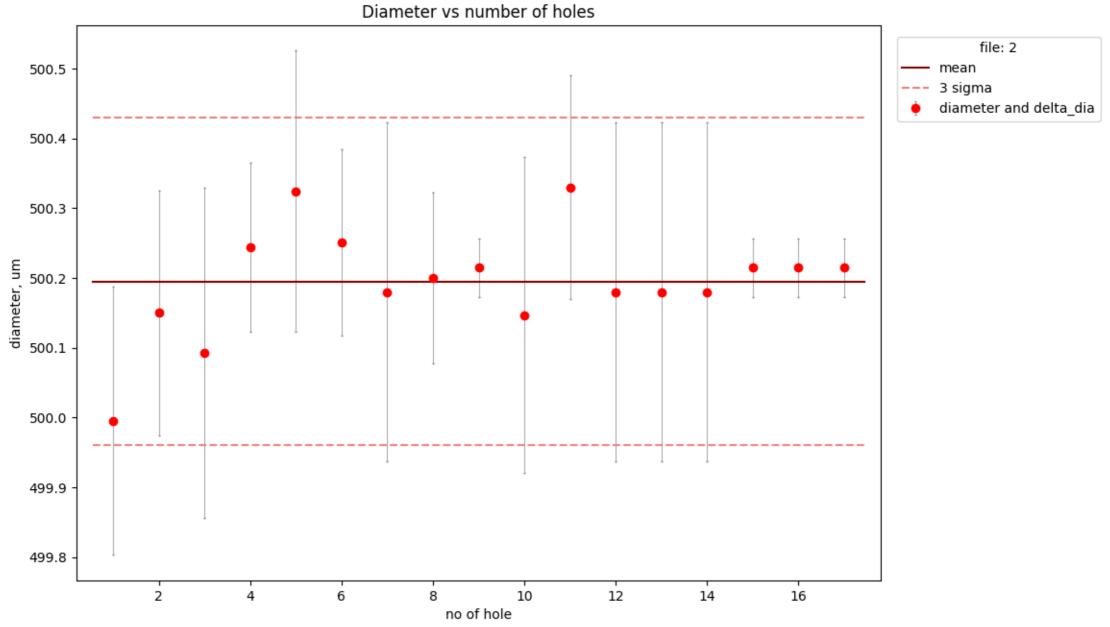
1st file: 2 2nd file: 3

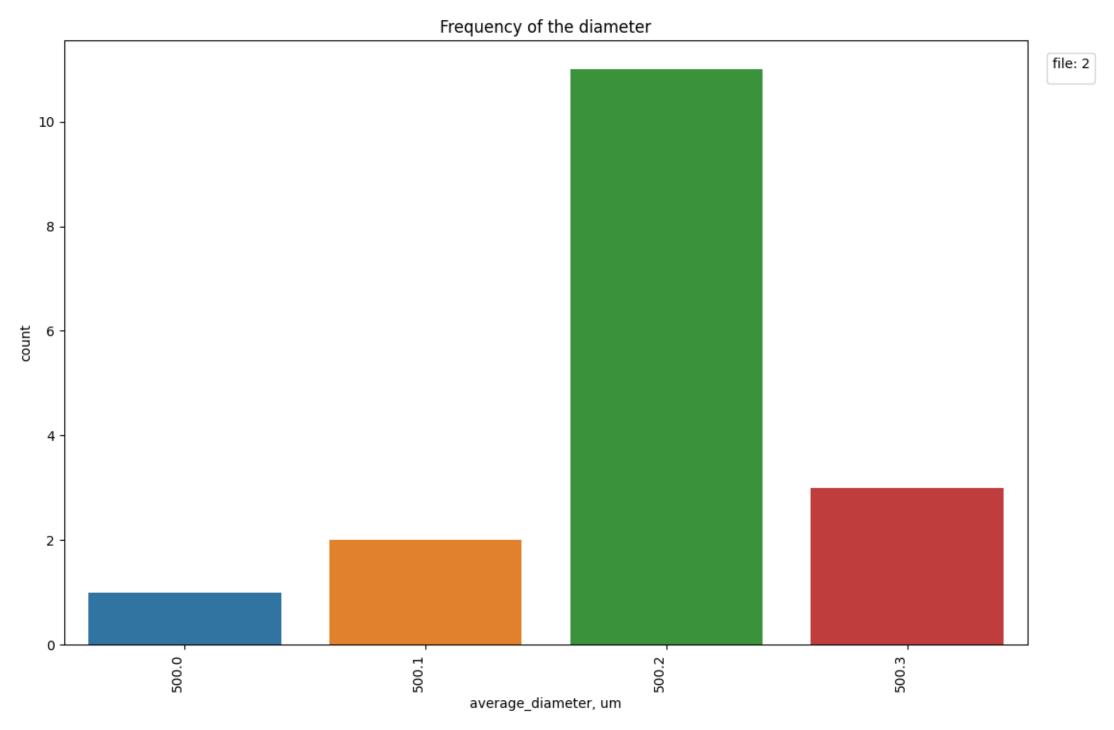
--- mean_1

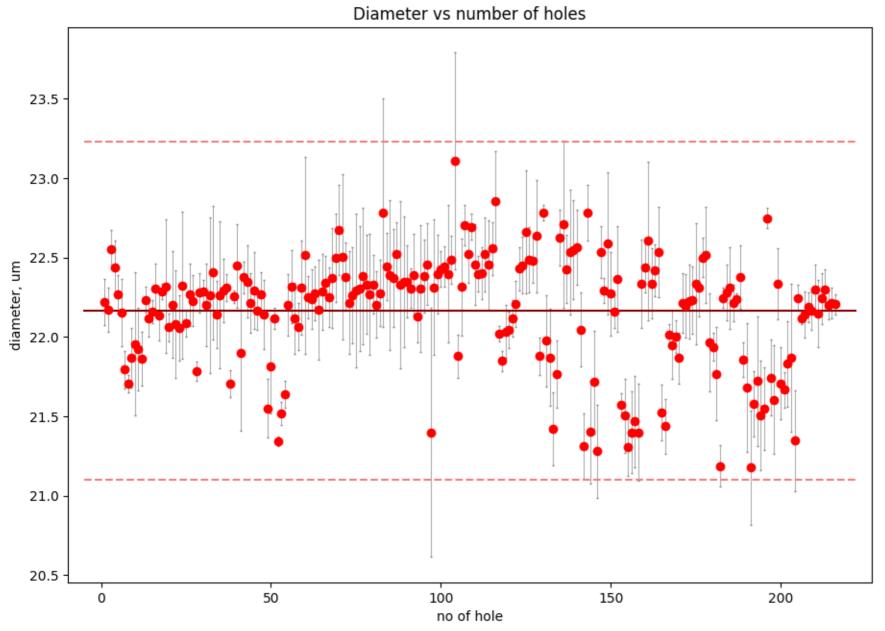
diameter_1 and delta_dia_1

-- mean_2

diameter_2 and delta_dia_2







file: 3

mean

3 sigma

diameter and delta_dia

Frequency of the diameter file: 3 48 42 36 30 t conut 24 18 12 6 0. 1. 2. 2. 2. 2. average_diameter, um 21.5 21.6 21.9 22.6 22.8 21.4 21.7 22.3 22.5 22.7 22.9 23.1